CTH214 Series

AC Input 4-Pin Half Pitch Mini-Flat Phototransistor Optocoupler

Features

- High isolation 5000 VRMS
- CTR flexibility available see order information
- DC input with transistor output
- Operating Temperature range - 55 ℃ to 110 ℃
- Regulatory Approvals
  - UL - UL1577 (E364000)
  - VDE - EN60747-5-5(VDE0884-5)
  - CQC – GB4943.1, GB8898
  - IEC60065, IEC60950
- Green Package

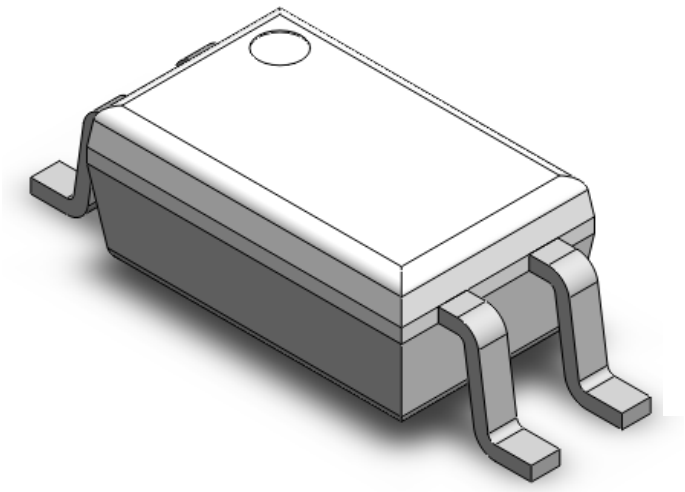
Description

The CTH214 series consists of a phototransistor optically coupled to two gallium arsenide Infrared-emitting diode, connected in inverse parallel in a 4-lead half pitch Mini-Flat package.

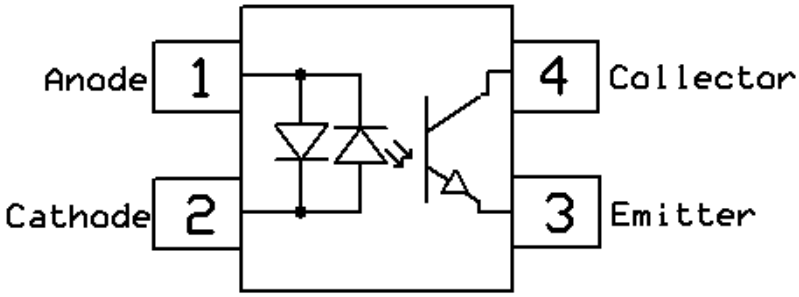
Applications

- Switch mode power supplies
- Computer peripheral interface
- Microprocessor system interface

Package Outline



Schematic



Absolute Maximum Rating at 25°C

Symbol	*Parameters*	*Ratings*	*Units*	*Notes*
V_{ISO}	Isolation voltage	3750	V_{RMS}	
P_{TOT}	Total power dissipation	200	mW	
T_{OPR}	Operating temperature	-55 ~ +110	°C	
T_{STG}	Storage temperature	-55 ~ +150	°C	
T_{SOL}	Soldering temperature	260	°C	
Emitter				
I_F	Forward current	±50	mA	
$I_{F(TRANS)}$	Peak transient current (≤1μs P.W,300pps)	1	A	
P_D	Emitter power dissipation	70	mW	
Detector				
P_D	Detector power dissipation	150	mW	
B_{VCEO}	Collector-Emitter Breakdown Voltage	80	V	
B_{VECO}	Emitter-Collector Breakdown Voltage	6	V	
I_C	Collector Current	50	mA	

Electrical Characteristics T_A = 25℃ (unless otherwise specified)

Emitter Characteristics

Symbol	Parameters	Test Conditions	Min	Typ	Max	Units	Notes
V_F	Forward voltage	I_F=±10mA		1.24	1.4	V	
C_{IN}	Input Capacitance	f= 1MHz	-	30	-	pF	

Detector Characteristics

Symbol	Parameters	Test Conditions	Min	Typ	Max	Units	Notes
B_{VCEO}	Collector-Emitter Breakdown	I_C= 100μA	80	-	-	V	
B_{VECO}	Emitter-Collector Breakdown	I_E= 100μA	6	-	-	V	
I_{CEO}	Collector-Emitter Dark Current	V_{CE}= 20V, I_F=0mA	-	-	100	nA	

Transfer Characteristics

Symbol	Parameters		Test Conditions	Min	Typ	Max	Units	Notes
CTR	Current Transfer Ratio	CTH214	I_F= ±1mA, V_{CE}= 5V	20	-	300	%	
		CTH214A		50	-	150		
	CTR Symmetry		I_F= ±1mA, V_{CE}= 5V	0.7	-	1.3		
$V_{CE(SAT)}$	Collector-Emitter Saturation Voltage		I_F= ±20mA, I_C= 1mA	-	0.04	0.2	V	
R_{IO}	Isolation Resistance		V_{IO}= 500V_{DC}	$5x10^{10}$	-	-	Ω	
C_{IO}	Isolation Capacitance		f= 1MHz	-	0.5	1	pF	

Switching Characteristics

Symbol	Parameters	Test Conditions	Min	Typ	Max	Units	Notes
t_r	Rise Time	I_C= 2mA, V_{CE}= 2V, R_L= 100Ω	-	6	-	μs	
t_f	Fall Time		-	8	-		

Typical Characteristic Curves

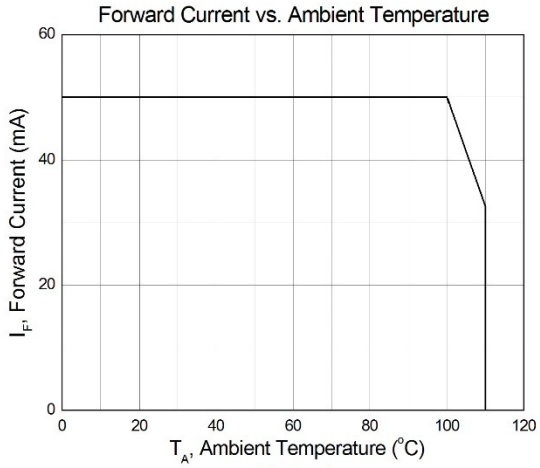


Figure 1

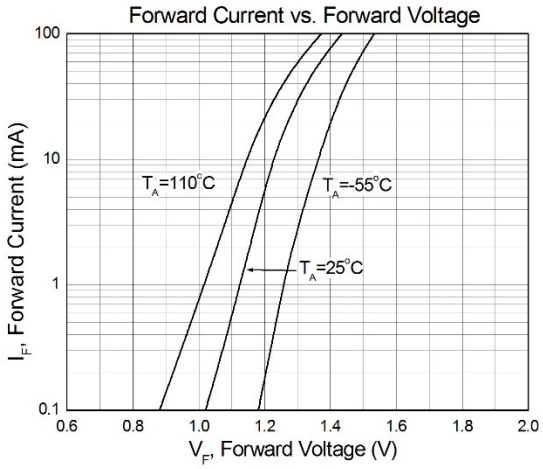


Figure 2

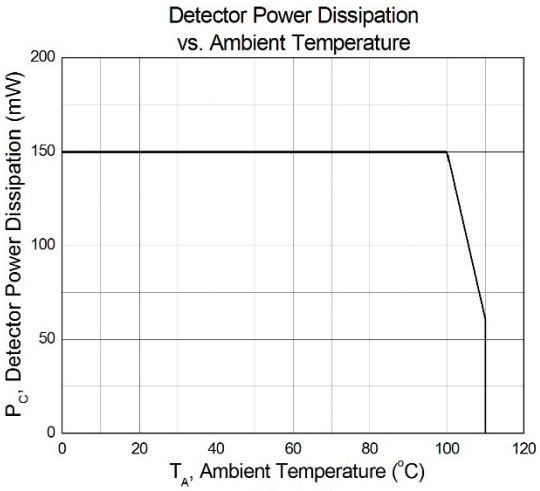


Figure 3

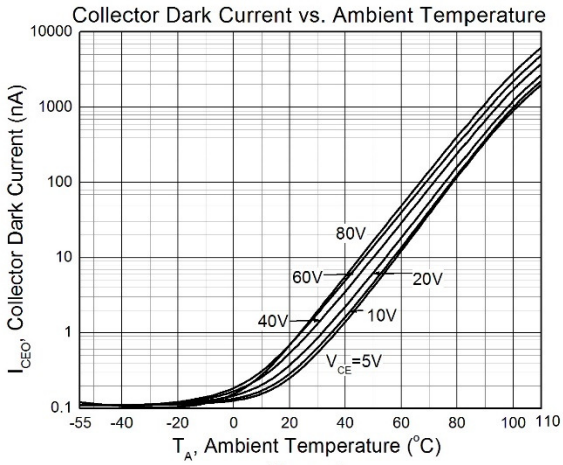


Figure 4

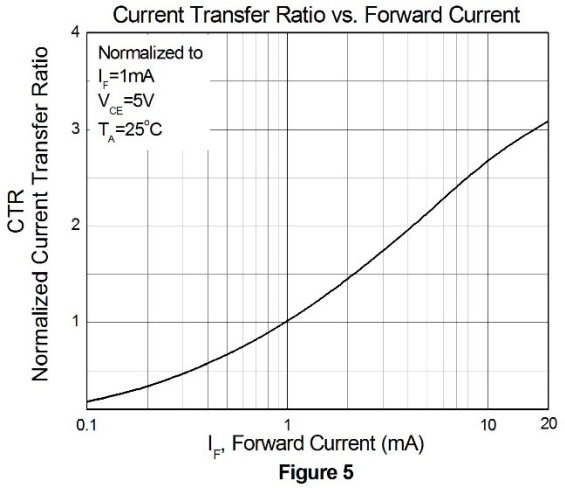


Figure 5

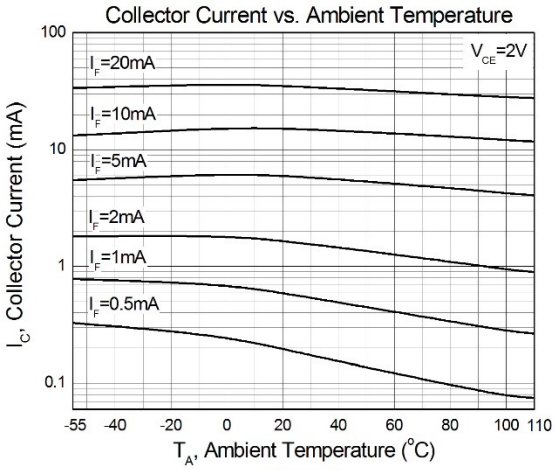


Figure 6

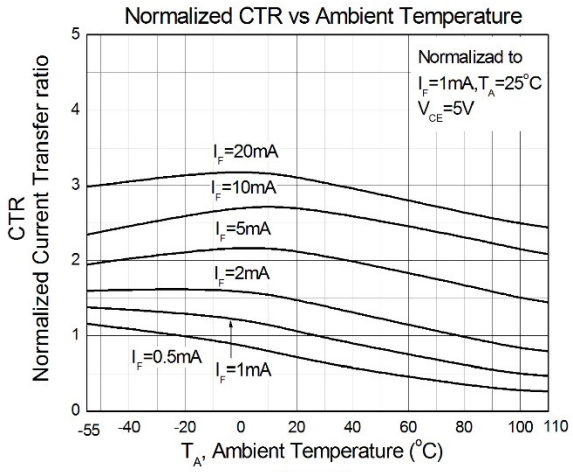


Figure 7

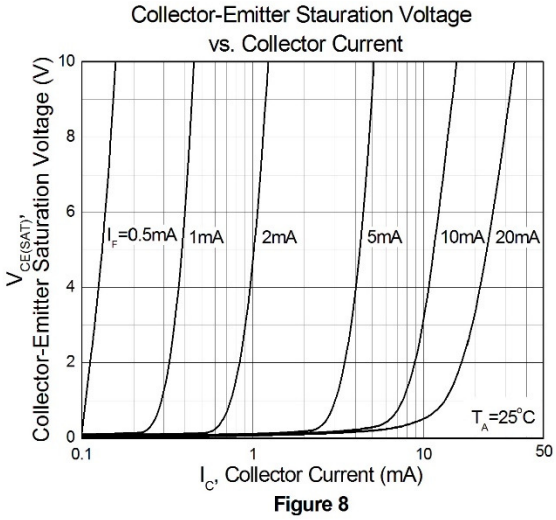


Figure 8

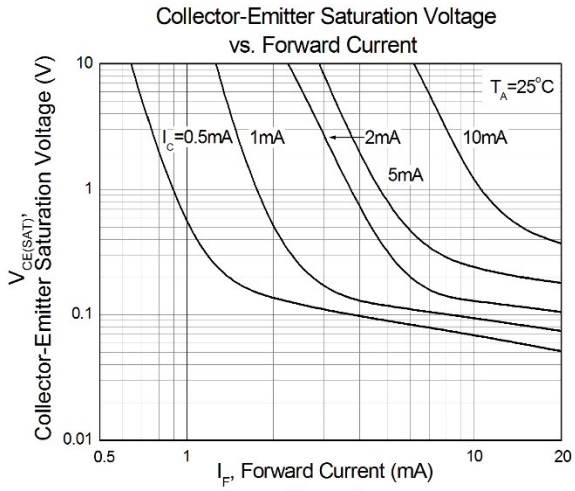


Figure 9

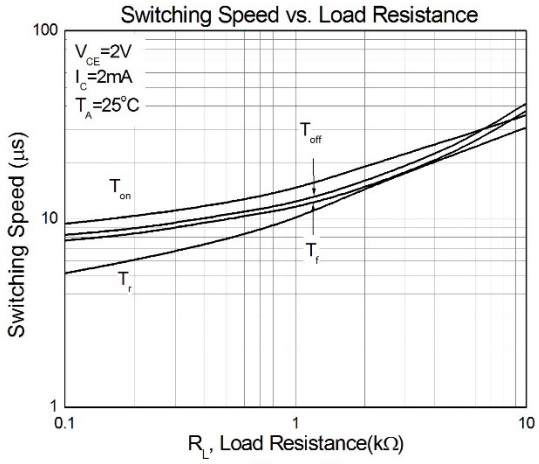


Figure 10

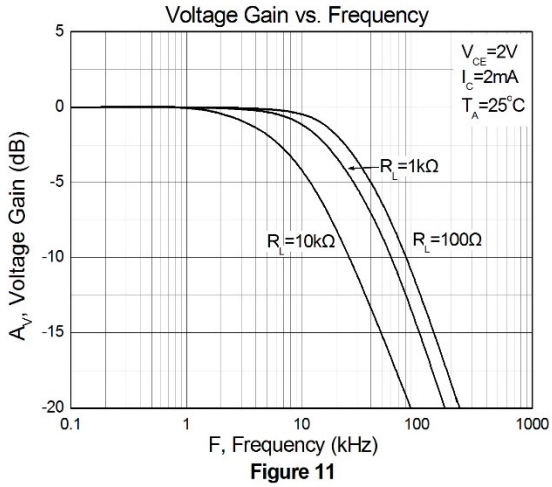


Figure 11

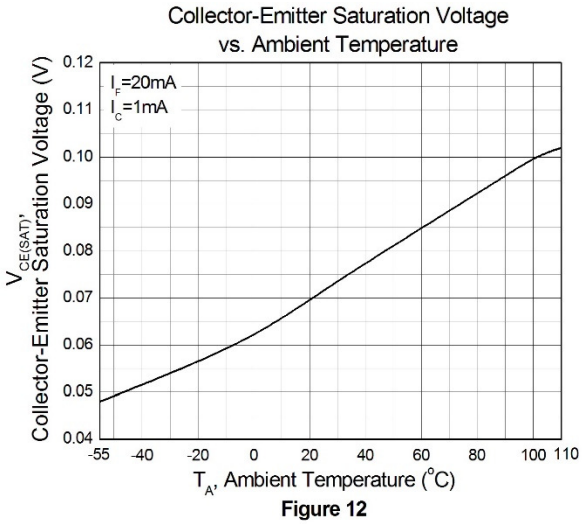
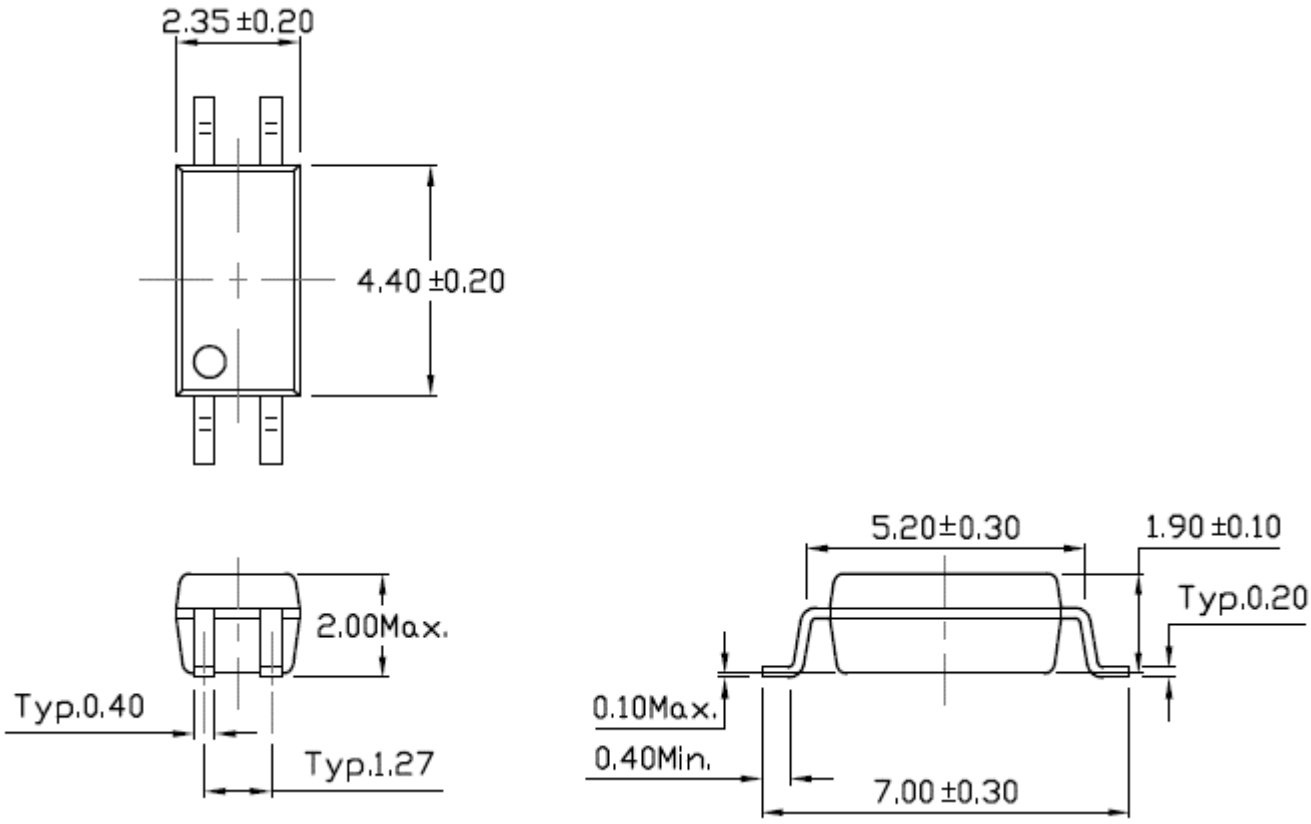
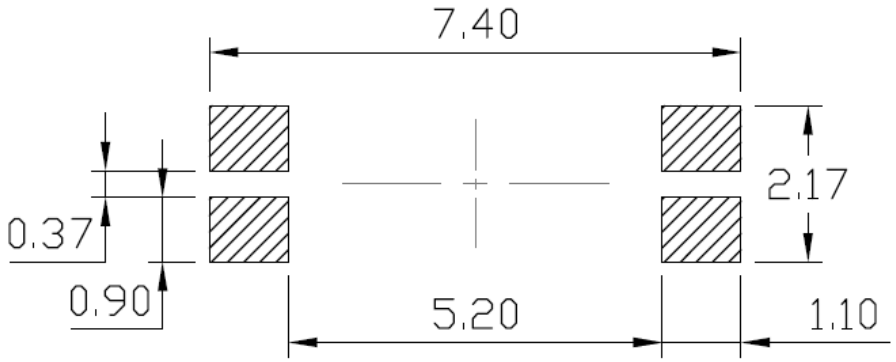


Figure 12

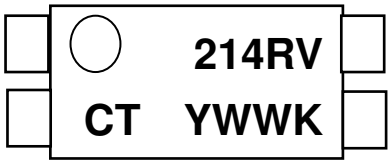
Package Dimension *Dimensions in mm unless otherwise stated*



Recommended Solder Mask *Dimensions in mm unless otherwise stated*



Marking Information



Note:

CT : Denotes “CT Micro”
214 : Product Number
R : CTR Rank
V : VDE Option
Y : Fiscal Year
WW : Work Week
K : Manufacturing Code

Ordering Information

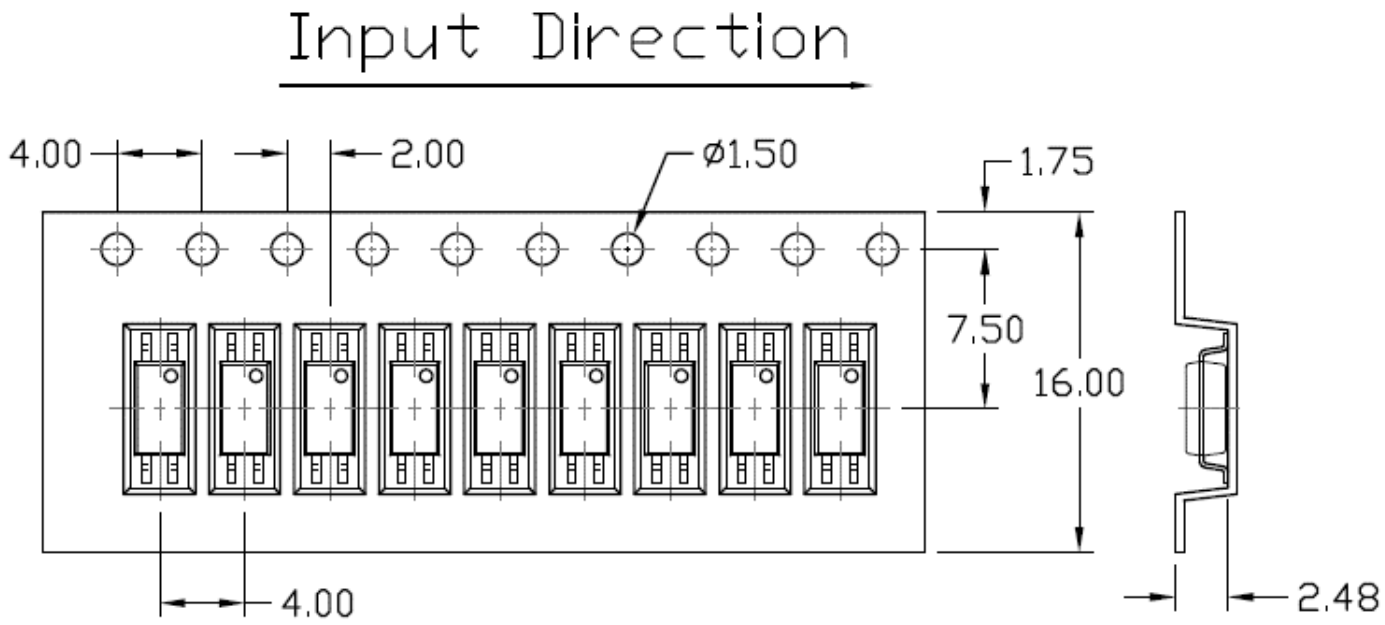
CTH214X(V)(Z)

X = Part No. (X=A or none)
V = VDE Option (V or none)
Z = Tape and reel option (T1 or T2)

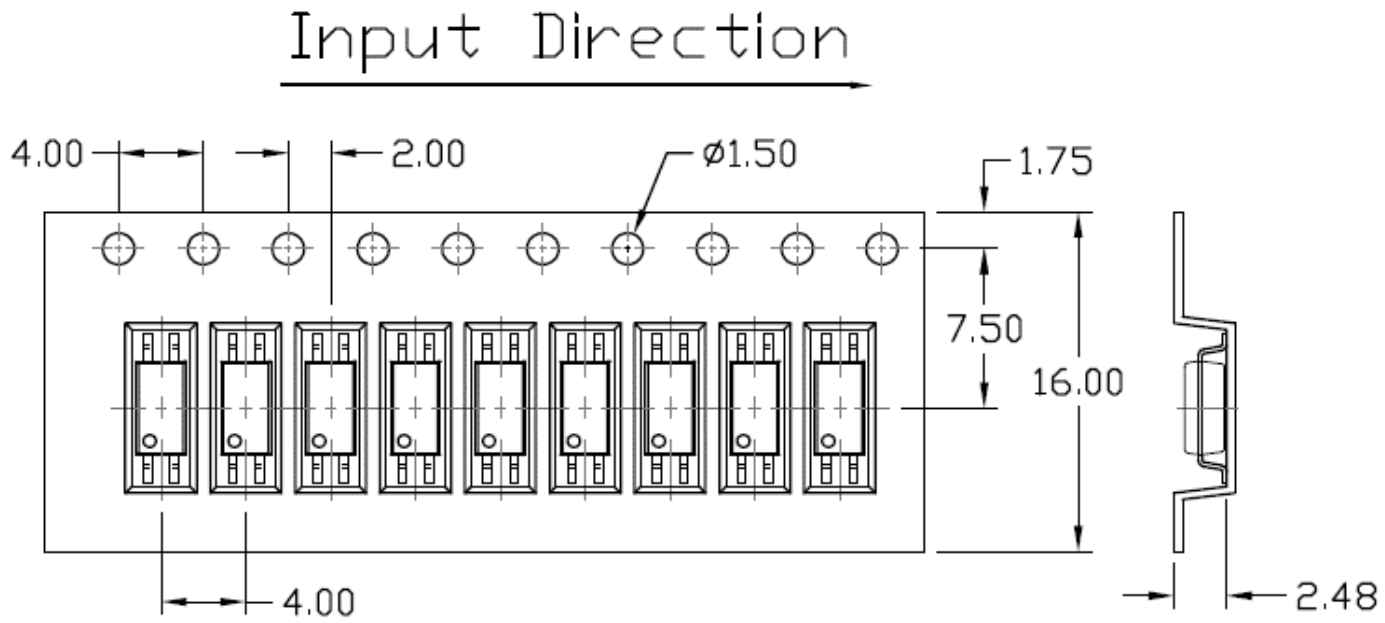
Option	*Description*	*Quantity*
T1	Surface Mount Lead Forming – With Option 1 Taping	5000 Units/Reel
T2	Surface Mount Lead Forming – With Option 2 Taping	5000 Units/Reel

Carrier Tape Specifications *Dimensions in mm unless otherwise stated*

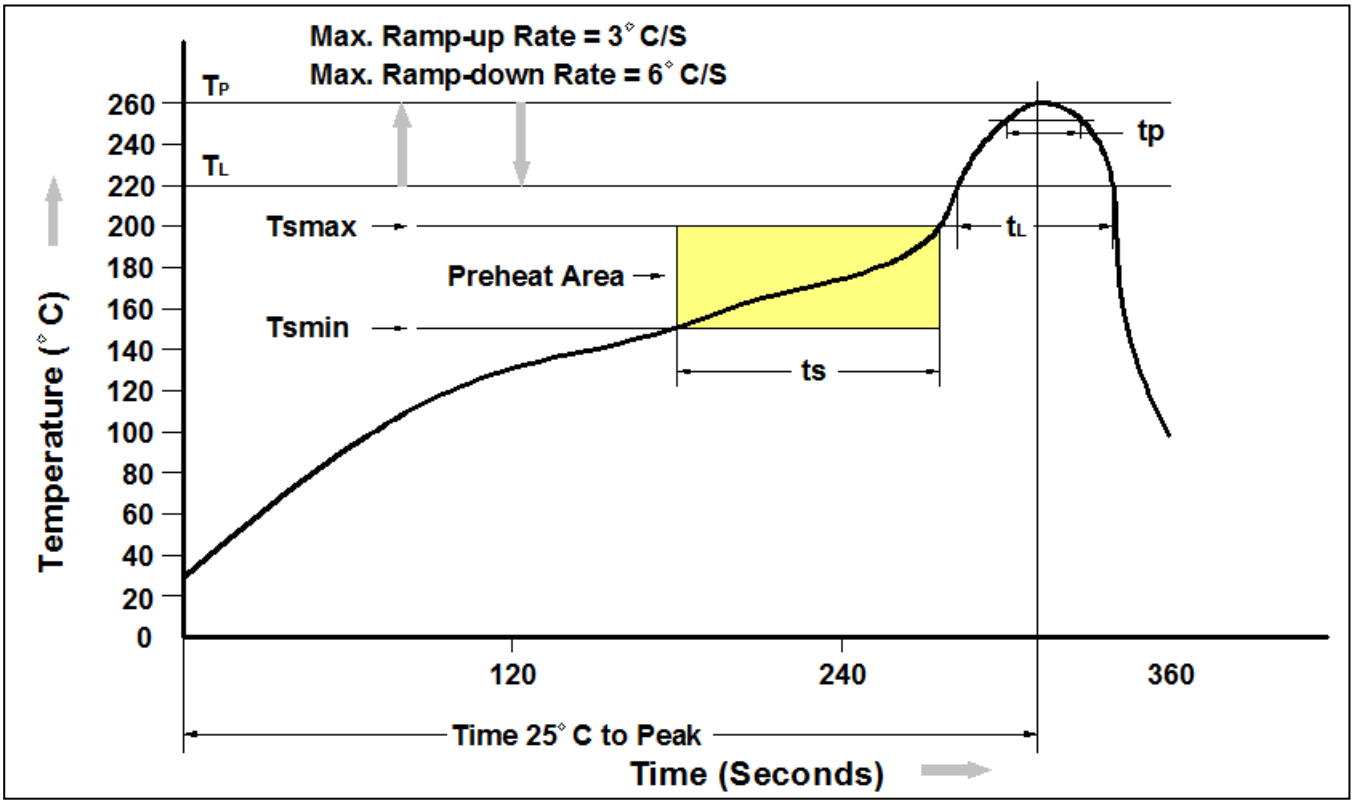
Option T1



Option T2



Reflow Profile



Profile Feature	Pb-Free Assembly Profile
Temperature Min. (Tsmin)	150℃
Temperature Max. (Tsmax)	200℃
Time (ts) from (Tsmin to Tsmax)	60-120 seconds
Ramp-up Rate (t_L to t_P)	3℃/second max.
Liquidous Temperature (T_L)	217℃
Time (t_L) Maintained Above (T_L)	60 – 150 seconds
Peak Body Package Temperature	260℃ +0℃ / -5℃
Time (t_P) within 5℃ of 260℃	30 seconds
Ramp-down Rate (T_P to T_L)	6℃/second max
Time 25℃ to Peak Temperature	8 minutes max.

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